

SOD89A

hermetically sealed glass package; axial leaded; 2 leads

8 February 2016

Package information

1. Package summary

Terminal position code	A (axial)
Package type descriptive code	GALF2
Package type industry code	GALF2
Package style descriptive code	LALF (glass axial (leaded) long form)
Package style suffix code	NA (not applicable)
Package body material type	L (glass)
Mounting method type	T (through-hole mount)
Issue date	20-6-1997

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	[tbd]	-	7	7	mm
Φ D	package diameter	[tbd]	-	5.5	5.5	mm
n ₂	actual quantity of termination	-	-	2	-	



2. Package outline

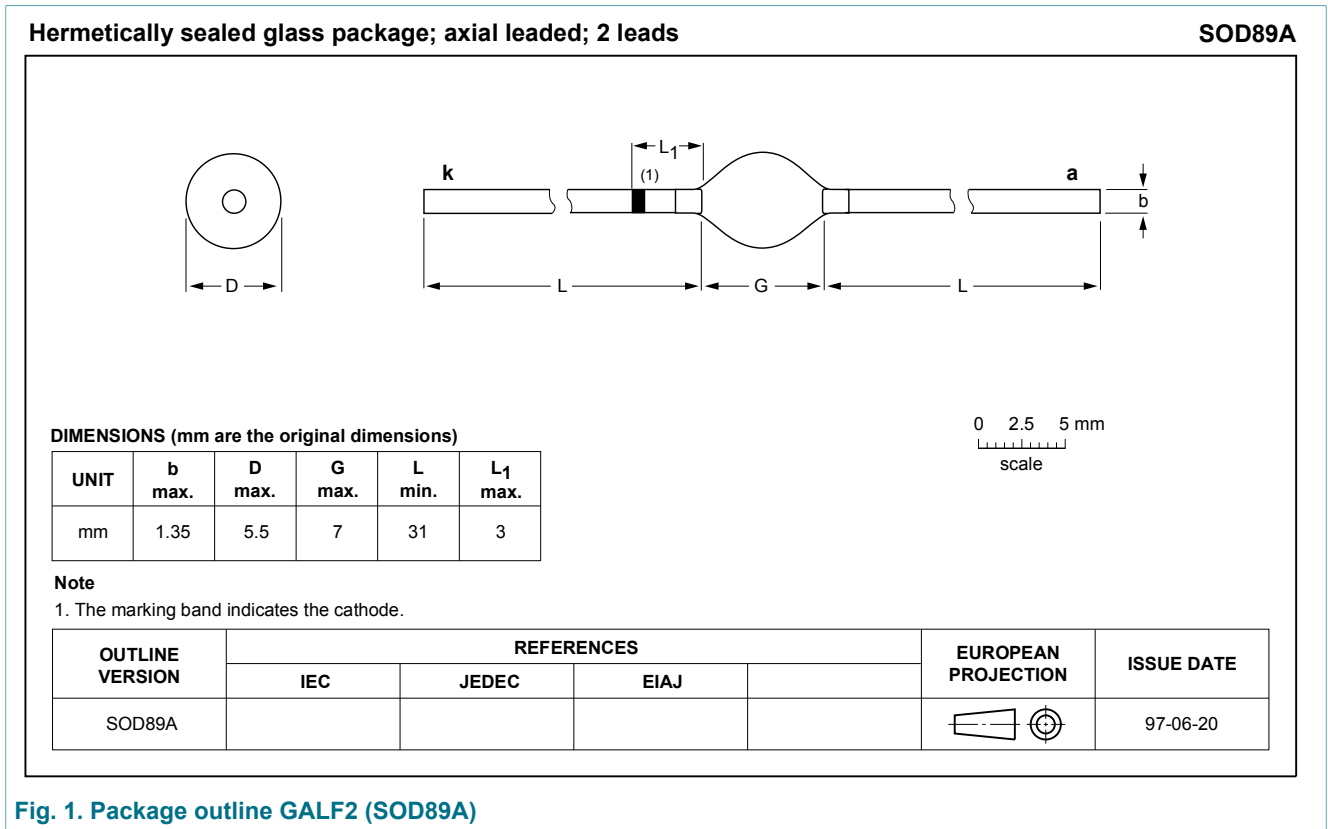


Fig. 1. Package outline GALF2 (SOD89A)

3. Legal information

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